

# 2SK2736

Silicon N Channel DV-L MOS FET  
High Speed Power Switching

# HITACHI

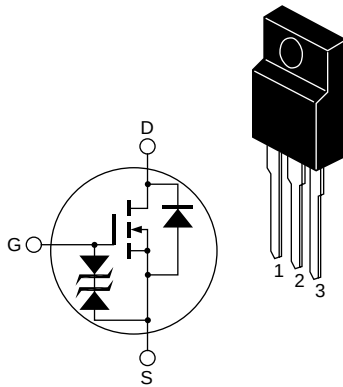
ADE-208-544  
1st. Edition

## Features

- Low on-resistance  
 $R_{DS(on)} = 20 \text{ m}\Omega$  typ. ( $V_{GS} = 10\text{V}$ ,  $I_D = 15 \text{ A}$ )
- 4V gate drive devices.
- High speed switching

## Outline

TO-220CFM



1. Gate
2. Drain
3. Source

Absolute Maximum Ratings (Ta = 25°C)

| Item                                      | Symbol                              | Ratings     | Unit |
|-------------------------------------------|-------------------------------------|-------------|------|
| Drain to source voltage                   | V <sub>DSS</sub>                    | 30          | V    |
| Gate to source voltage                    | V <sub>GSS</sub>                    | ±20         | V    |
| Drain current                             | I <sub>D</sub>                      | 30          | A    |
| Drain peak current                        | I <sub>D(pulse)</sub> <sup>*1</sup> | 120         | A    |
| Body to drain diode reverse drain current | I <sub>DR</sub>                     | 30          | A    |
| Channel dissipation                       | Pch <sup>*2</sup>                   | 25          | W    |
| Channel temperature                       | Tch                                 | 150         | °C   |
| Storage temperature                       | Tstg                                | −55 to +150 | °C   |

Notes: 1. PW ≤ 10μs, duty cycle ≤ 1 %  
2. Value at Tc = 25°C

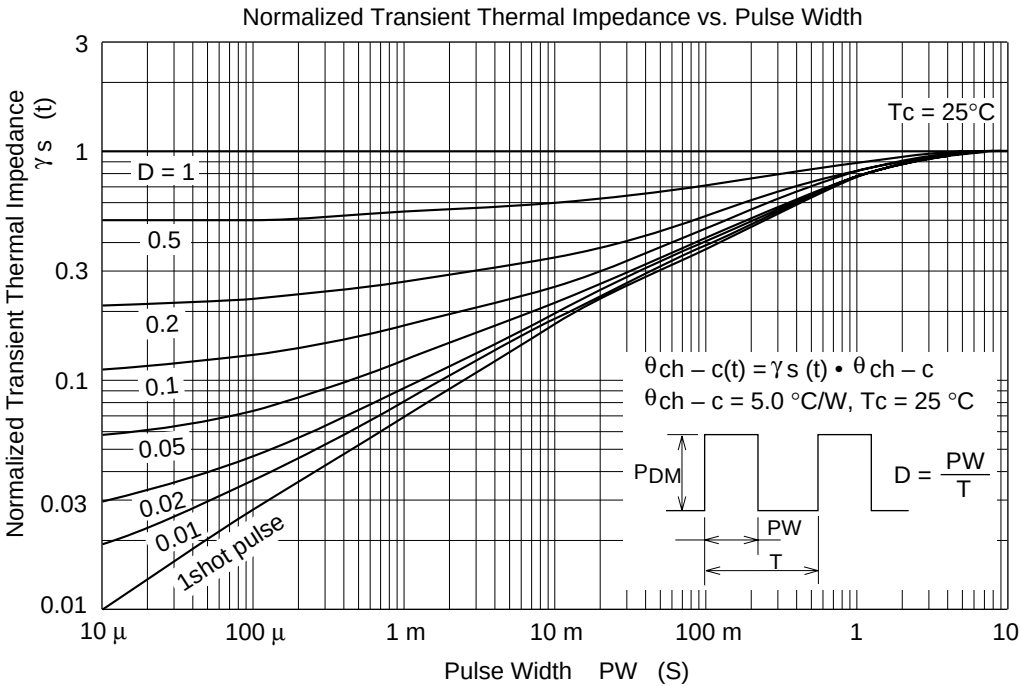
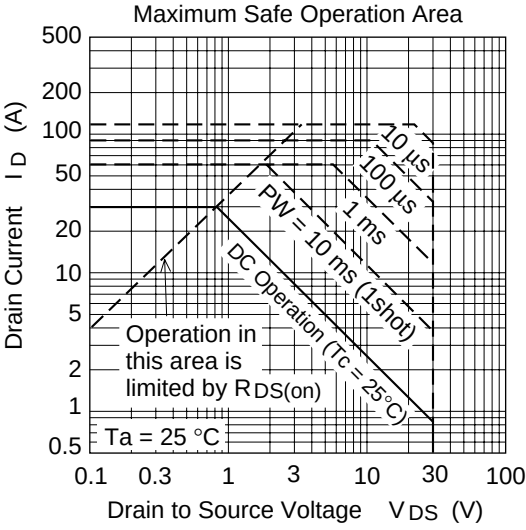
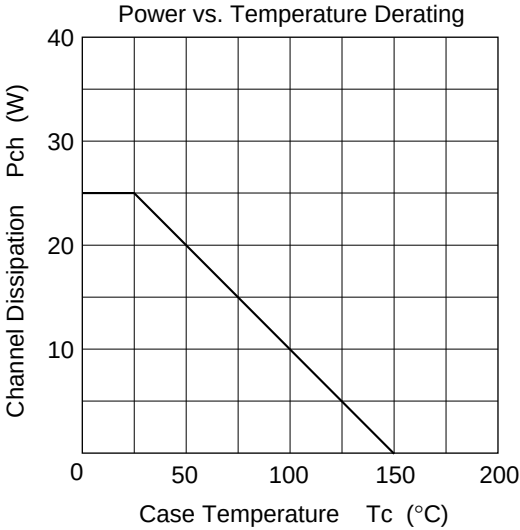
**Electrical Characteristics** ( $T_a = 25^\circ\text{C}$ )

| Item                                       | Symbol        | Min      | Typ | Max      | Unit             | Test Conditions                                                         |
|--------------------------------------------|---------------|----------|-----|----------|------------------|-------------------------------------------------------------------------|
| Drain to source breakdown voltage          | $V_{(BR)DSS}$ | 30       | —   | —        | V                | $I_D = 10\text{mA}$ , $V_{GS} = 0$                                      |
| Gate to source breakdown voltage           | $V_{(BR)GSS}$ | $\pm 20$ | —   | —        | V                | $I_G = \pm 100\mu\text{A}$ , $V_{DS} = 0$                               |
| Zero gate voltage drain current            | $I_{DSS}$     | —        | —   | 10       | $\mu\text{A}$    | $V_{DS} = 30\text{V}$ , $V_{GS} = 0$                                    |
| Gate to source leak current                | $I_{GSS}$     | —        | —   | $\pm 10$ | $\mu\text{A}$    | $V_{GS} = \pm 16\text{V}$ , $V_{DS} = 0$                                |
| Gate to source cutoff voltage              | $V_{GS(off)}$ | 1.0      | —   | 2.0      | V                | $I_D = 1\text{mA}$ , $V_{DS} = 10\text{V}$                              |
| Static drain to source on state resistance | $R_{DS(on)}$  | —        | 20  | 28       | $\text{m}\Omega$ | $I_D = 15\text{A}$ , $V_{GS} = 10\text{V}^{*1}$                         |
|                                            | $R_{DS(on)}$  | —        | 35  | 50       | $\text{m}\Omega$ | $I_D = 15\text{A}$ , $V_{GS} = 4\text{V}^{*1}$                          |
| Forward transfer admittance                | $ y_{fs} $    | 12       | 18  | —        | S                | $I_D = 15\text{A}$ , $V_{DS} = 10\text{V}^{*1}$                         |
| Input capacitance                          | $C_{iss}$     | —        | 750 | —        | pF               | $V_{DS} = 10\text{V}$                                                   |
| Output capacitance                         | $C_{oss}$     | —        | 520 | —        | pF               | $V_{GS} = 0$                                                            |
| Reverse transfer capacitance               | $C_{rss}$     | —        | 210 | —        | pF               | $f = 1\text{MHz}$                                                       |
| Turn-on delay time                         | $t_{d(on)}$   | —        | 16  | —        | ns               | $V_{GS} = 10\text{V}$ , $I_D = 15\text{A}$                              |
| Rise time                                  | $t_r$         | —        | 260 | —        | ns               | $R_L = 0.67\Omega$                                                      |
| Turn-off delay time                        | $t_{d(off)}$  | —        | 85  | —        | ns               |                                                                         |
| Fall time                                  | $t_f$         | —        | 90  | —        | ns               |                                                                         |
| Body to drain diode forward voltage        | $V_{DF}$      | —        | 1.0 | —        | V                | $I_F = 30\text{A}$ , $V_{GS} = 0$                                       |
| Body to drain diode reverse recovery time  | $t_{rr}$      | —        | 45  | —        | ns               | $I_F = 30\text{A}$ , $V_{GS} = 0$<br>$di_F/dt = 50\text{A}/\mu\text{s}$ |

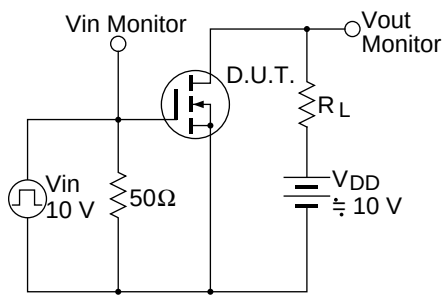
Note: 1. Pulse test

See characteristics curves of 2SK2684

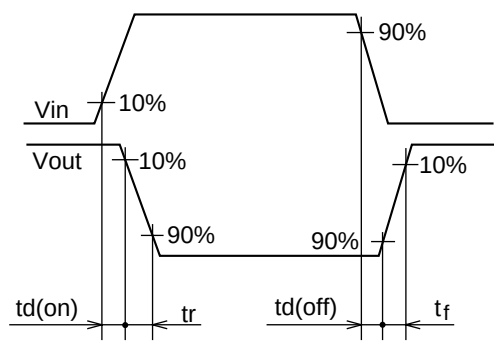
Main Characteristics



Switching Time Test Circuit

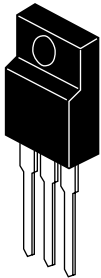
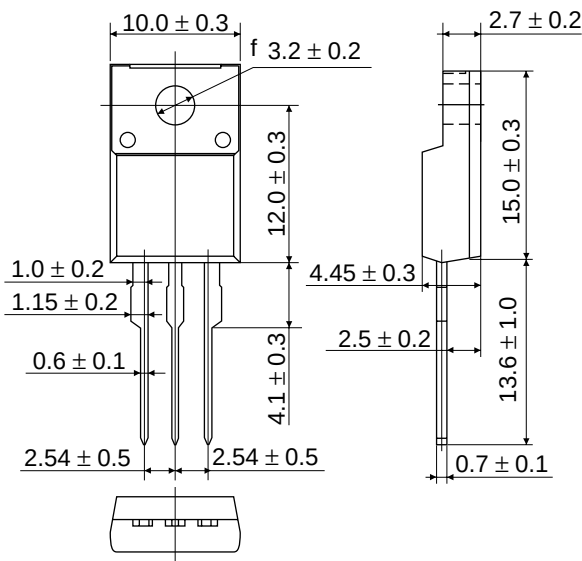


Waveform



Package Dimensions

Unit: mm



| Hitachi Code | TO-220CFM |
|--------------|-----------|
| EIAJ         | —         |
| JEDEC        | —         |

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# HITACHI

## Hitachi, Ltd.

Semiconductor & Integrated Circuits.  
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan  
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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## For further information write to:

|                                                                                                                                            |                                                                                                                                                                                                                                                                                                                                                                                         |
|--------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Hitachi Semiconductor (America) Inc.<br>179 East Tasman Drive,<br>San Jose, CA 95134<br>Tel: <1> (408) 433-1990<br>Fax: <1> (408) 433-0223 | Hitachi Europe GmbH<br>Electronic components Group<br>Dornacher Straße 3<br>D-85622 Feldkirchen, Munich<br>Germany<br>Tel: <49> (89) 9 9180-0<br>Fax: <49> (89) 9 29 30 00<br><br>Hitachi Europe Ltd.<br>Electronic Components Group.<br>Whitebrook Park<br>Lower Cookham Road<br>Maidenhead<br>Berkshire SL6 8YA, United Kingdom<br>Tel: <44> (1628) 585000<br>Fax: <44> (1628) 778322 |
|--------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|

Hitachi Asia Pte. Ltd.  
16 Collyer Quay #20-00  
Hitachi Tower  
Singapore 049318  
Tel: 535-2100  
Fax: 535-1533

Hitachi Asia Ltd.  
Taipei Branch Office  
3F, Hung Kuo Building, No.167,  
Tun-Hwa North Road, Taipei (105)  
Tel: <886> (2) 2718-3666  
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.  
Group III (Electronic Components)  
7/F., North Tower, World Finance Centre,  
Harbour City, Canton Road, Tsim Sha Tsui,  
Kowloon, Hong Kong  
Tel: <852> (2) 735 9218  
Fax: <852> (2) 730 0281  
Telex: 40815 HITEC HX

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